

201210US-2 DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:

OSAMU FURUKAWA, ET AL.

SERIAL NO: NEW DIV. APPLN.

FILED: HEREWITH

FOR: ELECTRONIC COMPONENT AND
METHOD OF PRODUCTION THEREOF

:

: GROUP UNIT:

:

: EXAMINER:

#2
Pradyumn
Chilam
8-27-01

PRELIMINARY AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

SIR:

Prior to initial examination on the merits, please amend the above-identified application
as follows:

IN THE CLAIMS

Please cancel Claims 1-165 without prejudice or disclaimer.

Please add new Claims 166-171 as follows:

--166. A surface acoustic wave device, comprising:

a printed circuit board possessing a first board surface and a second board surface, the
first board surface having a board wiring pattern and a board wiring pad which is thicker than
the board wiring pattern;

a surface acoustic wave element possessing a first element surface and a second element
surface, the first element surface including a transducer portion, an element wiring pad, and a
surface acoustic wave absorbing member formed outside of the element wiring pad, and the first
element surface being disposed in an opposite relation with respect to the first board surface; and

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